SN54HCT374, SN74HCT374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCLS005C - MARCH 1984 - REVISED DECEMBER 2002

- Operating Voltage Range of 4.5 V to 5.5 V
- High-Current 3-State True Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 22 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible
- Eight D-Type Flip-Flops in a Single Package
- Full Parallel Access for Loading

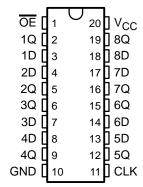
description/ordering information

These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

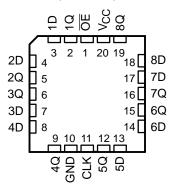
The eight flip-flops of the 'HCT374 devices are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels that were set up at the data (D) inputs.

An output-enable (\overline{OE}) input places the eight outputs in either a normal logic state (high or low

SN54HCT374 . . . J OR W PACKAGE SN74HCT374 . . . DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)



SN54HCT374 . . . FK PACKAGE (TOP VIEW)



logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N	Tube	SN74HCT374N	SN74HCT374N	
	0010 014	Tube	SN74HCT374DW	LIOTOZA	
400C to 050C	SOIC - DW	Tape and reel	SN74HCT374DWR	HCT374	
–40°C to 85°C	SOP - NS	Tape and reel	SN74HCT374NSR	HCT374	
	SSOP – DB Tape and re		SN74HCT374DBR	HT374	
	TSSOP - PW	Tape and reel	SN74HCT374PWR	HT374	
	CDIP – J	Tube	SNJ54HCT374J	SNJ54HCT374J	
−55°C to 125°C	CFP – W	Tube	SNJ54HCT374W	SNJ54HCT374W	
	LCCC – FK Tube		SNJ54HCT374FK	SNJ54HCT374FK	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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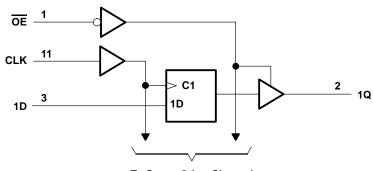


SCLS005C - MARCH 1984 - REVISED DECEMBER 2002

FUNCTION TABLE (each flip-flop)

	INPUTS	OUTPUT	
OE	CLK	Q	
L	1	Н	Н
L	\uparrow	L	L
L	H or L	Χ	Q_0
Н	Χ	Χ	Z

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see	e Note 1)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VCC	;) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	• • • • • • • • • • • • • • • • • • • •	±35 mA
Continuous current through V _{CC} or GND		±70 mA
Package thermal impedance, θ_{JA} (see Note 2):	DB package	70°C/W
	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
	PW package	83°C/W
Storage temperature range, T _{stg}		65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



SCLS005C - MARCH 1984 - REVISED DECEMBER 2002

recommended operating conditions (see Note 3)

			SN54HCT374			SN	74HCT3	74	LINUT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	V _{CC} = 4.5 V to 5.5 V	2			2			V
VIL	Low-level input voltage	V _{CC} = 4.5 V to 5.5 V			0.8			0.8	V
٧ _I	Input voltage		0		VCC	0		Vcc	V
٧o	Output voltage		0		VCC	0		Vcc	V
Δt/Δν	Input transition rise/fall time				500			500	ns
TA	Operating free-air temperature		-55	•	125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		v _{cc}	Т	A = 25°C	;	SN54HCT374		SN74HCT374		LINUT
PARAMETER				MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
V	V_{OH} $V_{I} = V_{IH} \text{ or } V_{IL}$	I _{OH} = -20 μA	45.1/	4.4	4.499		4.4		4.4		.,
VОН		$V_{I} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -6 \text{ mA}$ 4.5 V 3.98	4.3		3.7		3.84		V		
V		I _{OL} = 20 μA	45.77		0.001	0.1		0.1		0.1	.,
V _{OL}	VI = VIH or VIL	$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	V
lμ	$V_I = V_{CC}$ or 0		5.5 V		±0.1	±100		±1000		±1000	nA
loz	$V_O = V_{CC}$ or 0		5.5 V		±0.01	±0.5		±10		±5	μΑ
ICC	$V_I = V_{CC}$ or 0,	IO = 0	5.5 V			8		160		80	μΑ
∆l _{CC} †	One input at 0.5 V Other inputs at 0 o		5.5 V		1.4	2.4		3		2.9	mA
Ci			4.5 V to 5.5 V		3	10		10		10	pF

[†] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		v _{cc}		25°C	SN54H	CT374	SN74H	CT374	LINIT
				MAX	MIN	MAX	MIN	MAX	UNIT
4	Clock frequency	4.5 V		31		21		25	MHz
fclock		5.5 V		36		23		28	
	Pulse duration, CLK high or low	4.5 V	16		24		20		ns
t _W		5.5 V	14		22		18		
	Catura times, data hafara CLIVA	4.5 V	20		30		25		
t _{su}	Setup time, data before CLK↑	5.5 V	17		27		23		ns
4.	Hold time, data after CLK↑	4.5 V	10		10		10		ns
th		5.5 V	10		10		10		



SN54HCT374, SN74HCT374 OCTAL EDGÉ-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCLS005C - MARCH 1984 - REVISED DECEMBER 2002

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

24244555	FROM	то	.,	T	գ = 25°C	;	SN54H	CT374	SN74H	CT374	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			4.5 V	31	36		21		25		N 41 1-
f _{max}			5.5 V	36	40		23		28		MHz
	CL K	A O	4.5 V		30	36		54		45	
^t pd	CLK	Any Q	5.5 V		25	32		49		41	ns
		ŌĒ Any Q	4.5 V		26	30		45		38	
t _{en}	OE		5.5 V		23	27		41		34	ns
	ŌĒ	A O	4.5 V		23	30		45		38	
^t dis	OE	Any Q	5.5 V		22	27		41		34	ns
		Anv	4.5 V		10	12		18		15	
t _t		Any Q	5.5 V		9	11		16		14	ns

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

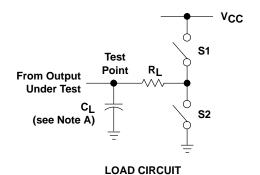
DADAMETER	FROM	то		T,	չ = 25°C	;	SN54H	CT374	SN74H	CT374		
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
	01.14	A O	4.5 V		40	46		69		58		
^t pd	CLK	Any Q	5.5 V		35	41		62		52	ns	
	<u>OE</u>	A O	4.5 V		34	40		60		50		
t _{en}	OE OE	Any Q	Any Q	5.5 V		29	36		54		45	ns
4.		Any Q	4.5 V		18	42		63		53	20	
t _t			5.5 V		16	38		57		48	ns	

operating characteristics, $T_A = 25^{\circ}C$

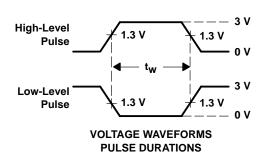
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per flip-flop	No load	85	pF

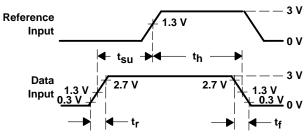


PARAMETER MEASUREMENT INFORMATION

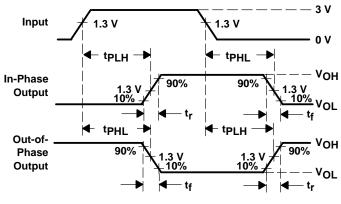


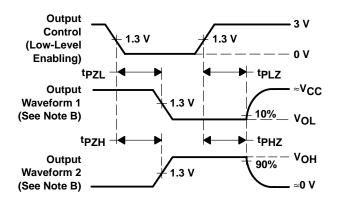
PARA	PARAMETER		CL	S1	S2	
	^t PZH	1 k Ω	50 pF	Open	Closed	
^t en	^t PZL	1 1 1	150 pF	Closed	Open	
4	tPHZ	1 k Ω	50 pF	Open	Closed	
^t dis	tPLZ	1 K22	50 pr	Closed	Open	
t _{pd} or t _t			50 pF or 150 pF	Open	Open	





VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT RISE AND FALL TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, ZO = 50 Ω , t_f = 6 ns, t_f = 6 ns.
- D. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. tp7I and tp7H are the same as ten.
- H. tpLH and tpHL are the same as tpd.

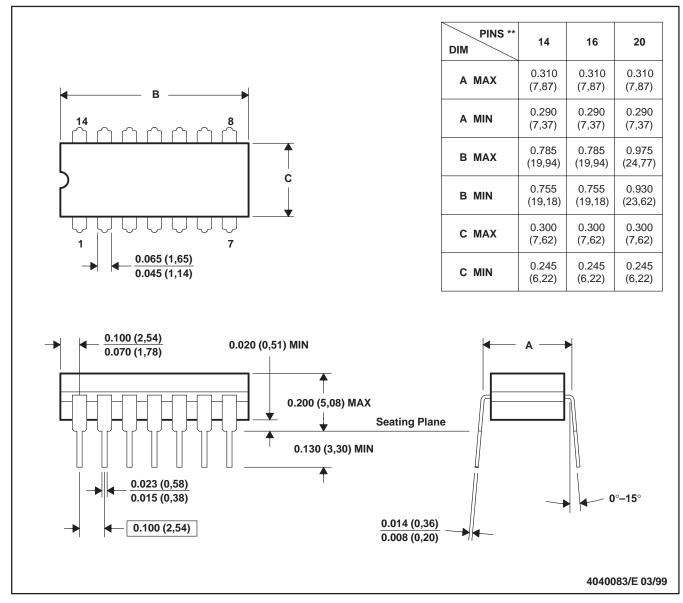
Figure 1. Load Circuit and Voltage Waveforms



J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

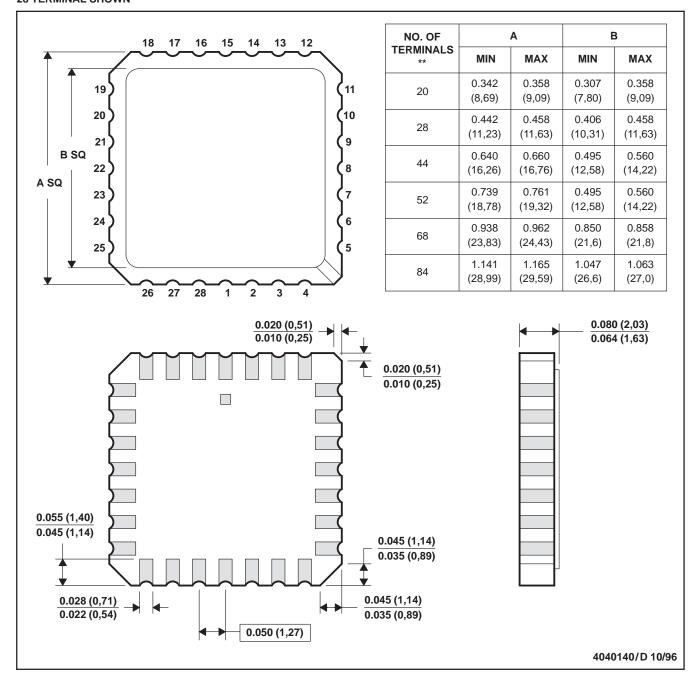
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, and GDIP1-T20



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



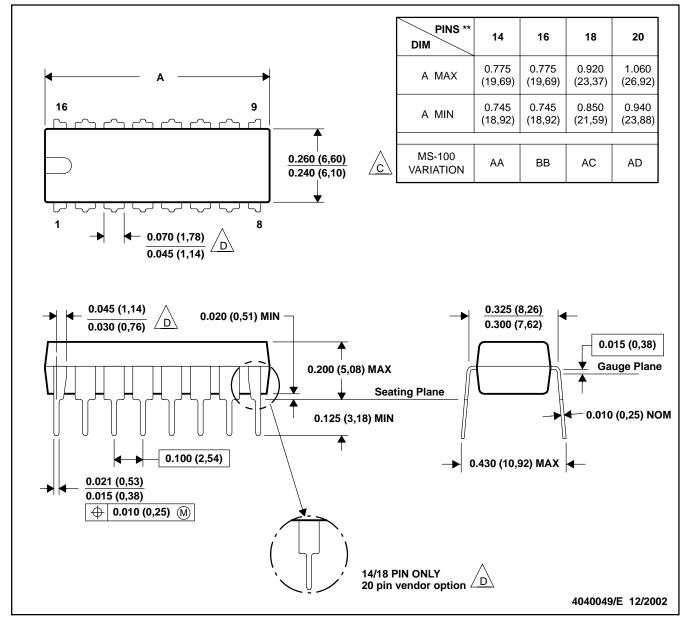
- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004



N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

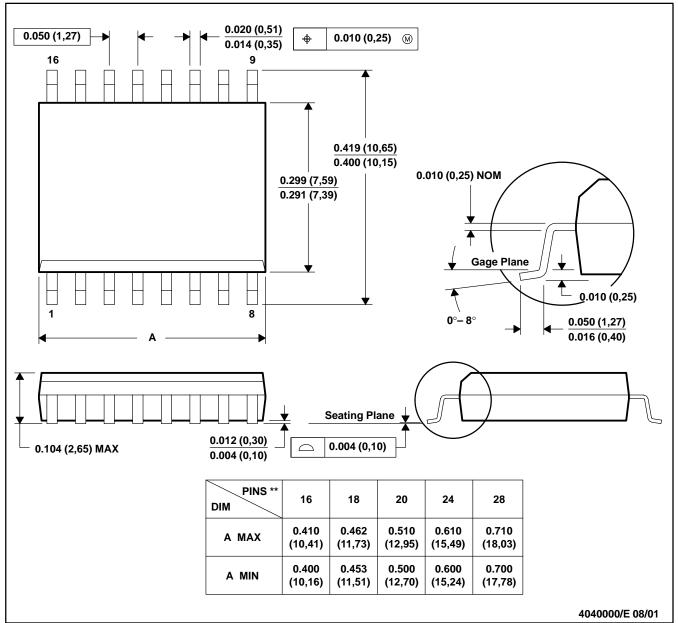
Falls within JEDEC MS-001, except 18 and 20 pin minimum body Irngth (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



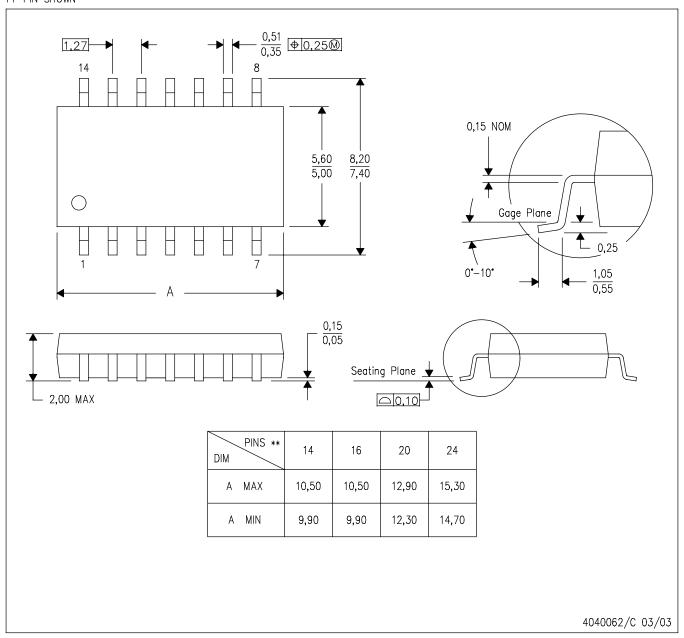
NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013

14-PIN SHOWN



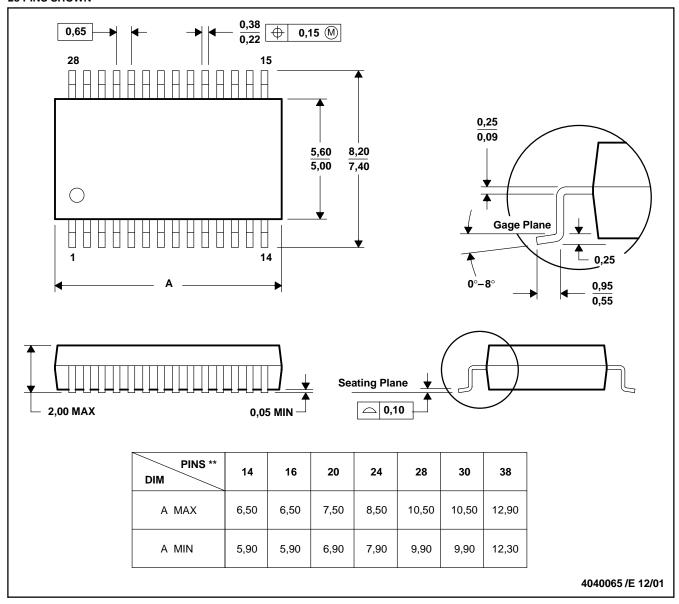
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

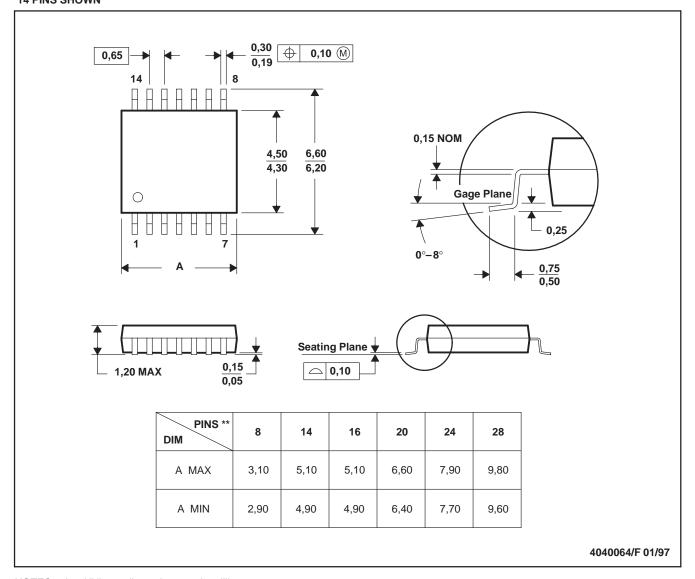
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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